

ABSTRACT OF THE DISCLOSURE

It is an object of the present invention is to provide a method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component which can prevent a ceramic green sheet from being deformed and destroyed and prevent a solvent contained in an electrode paste from sinking into a ceramic green sheet, thereby enabling manufacture of a multi-layered unit including a ceramic green sheet and an electrode layer laminated to each other in a desired manner.

The method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component according to the present invention includes a step of forming a ceramic green sheet on the surface of a first carrier film, a step of forming a release layer on the surface of a second carrier film including a surface-treated region on which a surface treatment is performed for improving releasability and non-surface-treated regions on which no surface treatment is performed on both sides of the surface-treated region and having a width substantially equal to that of the first carrier film, a step of forming an electrode layer in a predetermined pattern and a spacer layer in a complementary pattern to that of the electrode layer on the surface of the release layer, thereby forming an inner electrode layer, a step of forming an adhesive layer on the surface of a third carrier film having a width substantially equal to that of the second carrier film, a step of transferring the adhesive layer formed on the third carrier film onto the surface of the inner electrode layer, and a step of transferring the ceramic green sheet formed on the surface of the first carrier film onto the adhesive layer transferred on the surface of the inner electrode layer formed on the surface of the second carrier film, thereby fabricating a

multi-layered unit including the ceramic green sheet and the inner electrode layer laminated onto each other, wherein the adhesive layer is formed by coating the surface of the third carrier film with an adhesive agent solution so that the width of the adhesive layer is narrower than
5 the width of the third carrier film by at least 2α where α is a positive value, wider than the width of the ceramic green sheet formed on the surface of the first carrier film and the widths of the release layer and the inner electrode layer formed on the surface of the second carrier film by at least 2α and wider than the width of the surface-treated region of the
10 second carrier film by at least 2α .